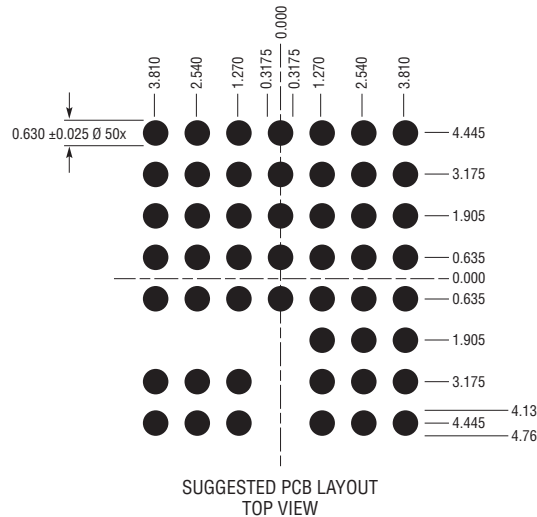
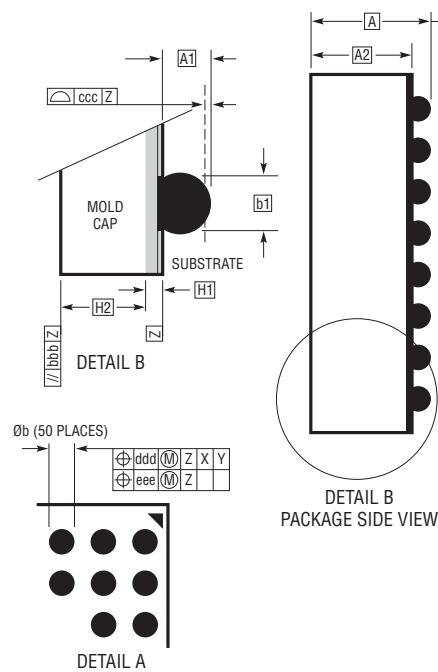
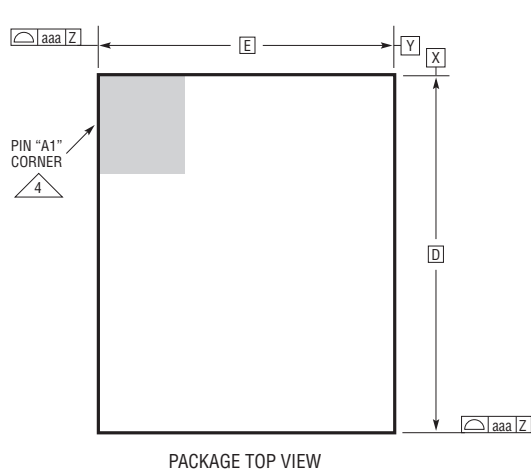
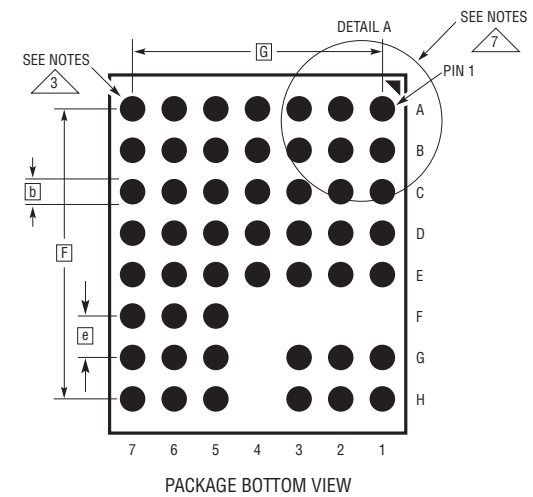


**BGA Package**  
**50-Lead (11.25mm × 9.00mm × 3.42mm)**  
 (Reference LTC DWG # 05-08-1883 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.22	3.42	3.62	
A1	0.50	0.60	0.70	
A2	2.72	2.82	2.92	
b	0.71	0.78	0.85	
b1	0.60	0.63	0.66	
D		11.25		
E		9.0		
e		1.27		
F		8.89		
G		7.62		
H1	0.27	0.32	0.37	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 50				



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  2. ALL DIMENSIONS ARE IN MILLIMETERS
  - 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
  - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
  5. PRIMARY DATUM -Z- IS SEATING PLANE
  6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
  - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

